

808nm 300W VCSEL Diode VD-0808I-300W-XX-2A0

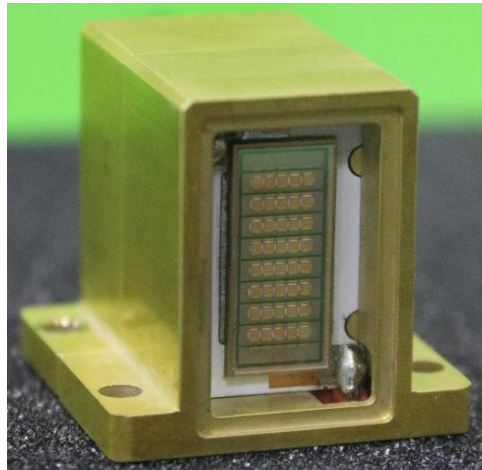
FEATURES

- 808nm single wavelength
- Low wavelength drift
- Circular Spot
- SMD package
- High reliability
- Easy to collimate

APPLICATIONS

- Scanning LiDAR
- Pump source of solid-state laser
- Laser machining
- 3D sensors
- Cosmetics i.e. Hair removal
- Range finder sensors

Part Number	Description
VD-0808I-300W-6K-2A0	808nm 300W VCSEL Diode
VD-0808I-300W-1U-2A0+Case	808nm 300W Wat



PRODUCT IDENTIFY

Code Rules

<u>VD</u>	-	<u>0808</u>	!	-	<u>300</u>	<u>W</u>	-	<u>X</u>	<u>X</u>	-	<u>2</u>	<u>A</u>	<u>0</u>
①	-	②	③	-	④	⑤	-	⑥	⑦	-	⑧	⑨	⑩
													Annex, 0
													Product Version, A
													Accessories, 2=CW mode
													Package type, U=1532, T=T-mount
													Substrate, 1= AlN, 6= Cu
													Power units, W = Watts
													Power value, 300
													Classification, I=Industrial application
													Wavelength, 808nm
													Header, short form of <u>VCSEL diode</u>

I. Absolute maximum ratings

Parameter	Symbol	Rating	Unit
Case Operating Temperature	T_{op}	-40 to +85	°C
Storage Temperature	T_{sto}	-40 to +105	°C
Reflow Soldering Temperature	T_{sdr}	180°C (10s)	°C
Reverse Voltage	V_r	25	V
Maximum Continuous Current	I_{max}	50	A
ESD exposure (Human body) model	ESD	2k	V

Note:

- Stresses greater than those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or other conditions above those indicated in the operations section for extended periods of time may affect reliability.
- In its maximum rating diode laser operation could damage its performance or cause potential safety hazard such as equipment failure.
- Electrostatic discharge is the main reason for the laser fault of the diode. Take effective precautions against ESD. When dealing with laser diodes, use the wrist strap, grounding work surface and strict antistatic technology.

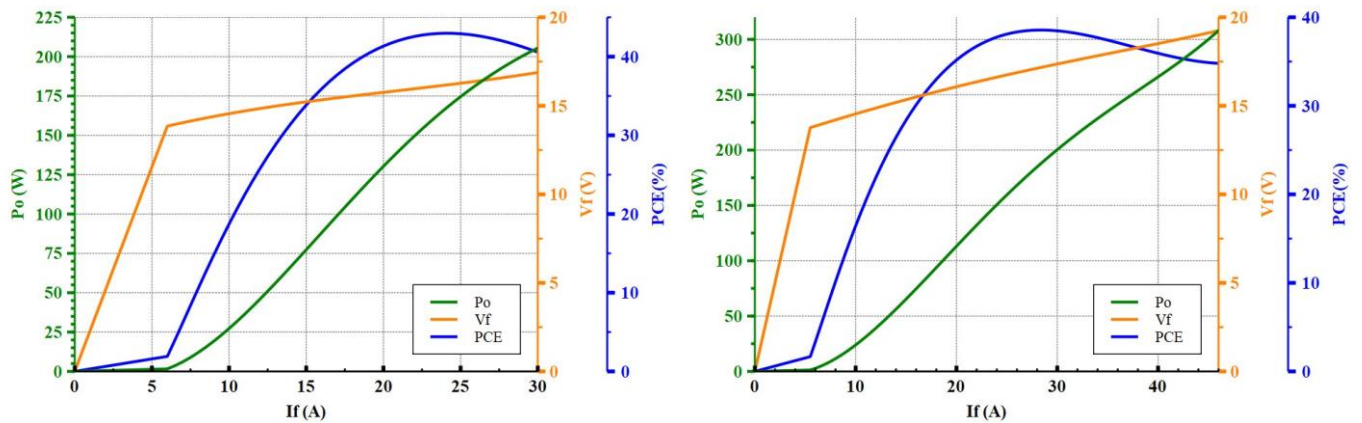
II. Optical-electrical characteristics @25°C

VCSEL Parameters	Symbol	Conditions	Min.	Typ.	Max.	Units	
CW mode							
Optical Power Output	P_o	$I_F = 29A$	-	200	-	W	
Threshold Current	I_{th}	-	-	6	-	A	
Forward Current	I_F	-	-	29	-	A	
Slope Efficiency	-	-	-	8.7	-	W/A	
Power Conversion Efficiency	η	$I_F = 29A$	-	42	-	%	
Laser Forward Voltage	V_F	$I_F = 29A$	-	17	-	V	
Series Resistance	R_S	$I_F = 29A$	-	0.1	-	Ω	
Emission area	-	-	-	17.6x8.4	-	mm	
Beam Angle	(1/e ²)	θ	$I_F = 29A$	-	25	-	Degrees
	FWHM	θ	$I_F = 29A$	-	-	-	Degrees
Peak Wavelength	λ_P	$P_o = 200W$	800	808	816	nm	
Wavelength shift	$\partial\lambda_P/\partial T$	$I_F = 29A$	-	-	0.07	nm/°C	
Pulse Mode (100ms, 1Hz, Duty cycle 10%)							
Optical Peak Power	P_o	$I_F = 45A$	-	300	-	W	
Forward Current	I_F	-	-	45	-	A	
Slope Efficiency	-	-	-	7.7	-	W/A	
Laser Forward Voltage	V_F	$I_F = 45A$	-	19	-	V	
Power Conversion Efficiency	η	$I_F = 45A$	-	35	-	%	

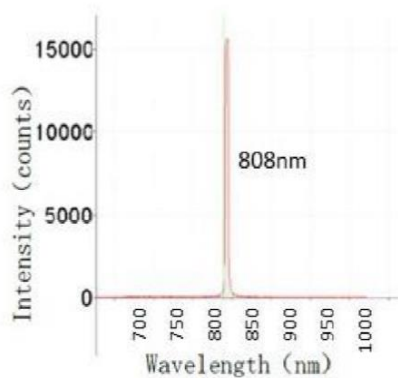
Series Resistance	R_S	$I_F = 45A$	-	0.1	-	Ω
Soldering Temperature	-	-	-	-	180 (10s)	$^{\circ}C$
Substrate	AlN, Cu					

Note: Electro-Optical Characteristic with a package or diffuser would require further evaluation. Values are based on limited sample size and estimated values.

III. Typical Performance LIV curve & Wavelength

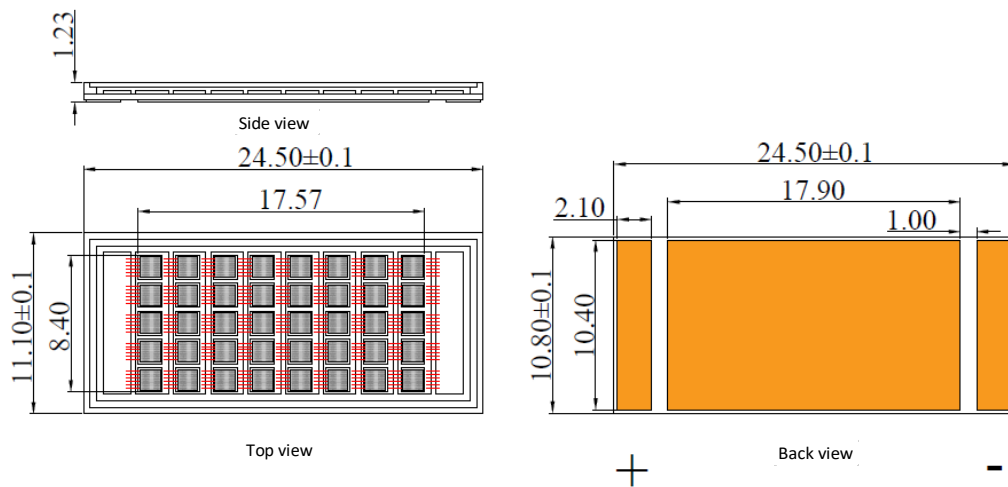


(right) : CW mode; (left) : Pulse mode at Pulse width 100ms & Duty cycle 10%.



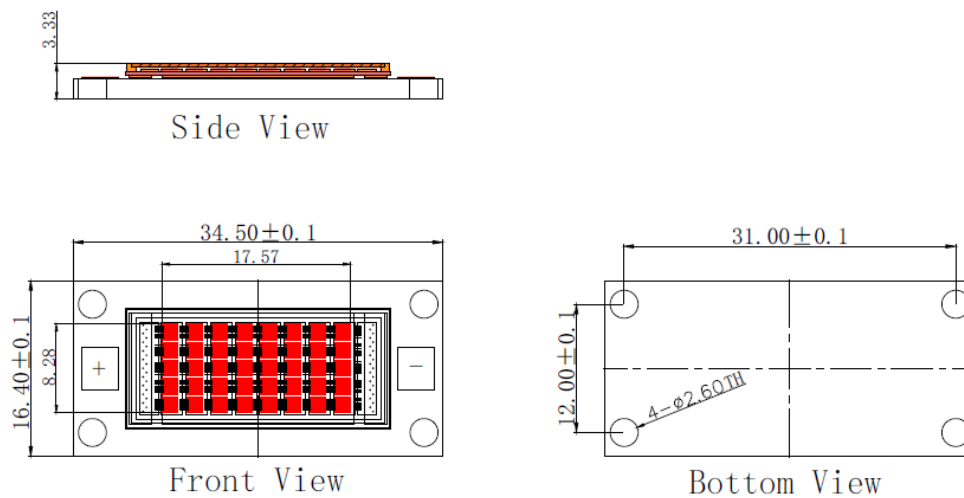
IV. Mechanical Schematics

VD-0808I-300W-1U-3A0 with Substrate 1=AIN and Package U=1532 (unit: mm)

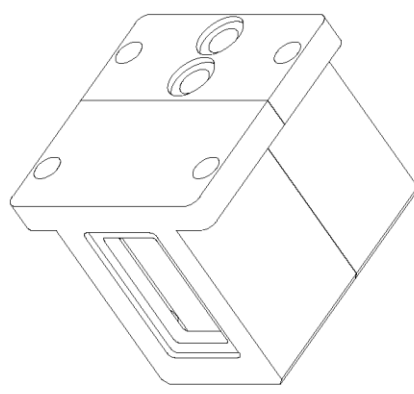
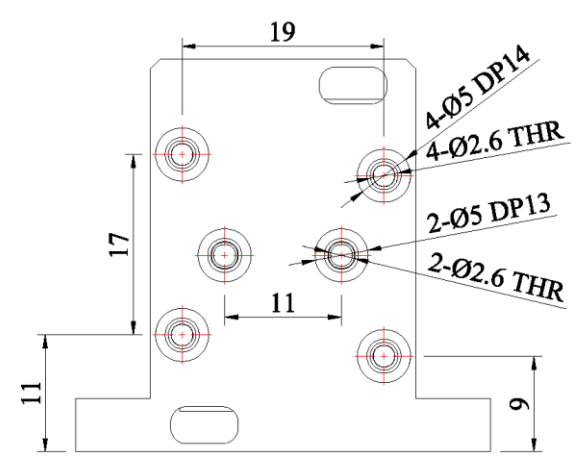
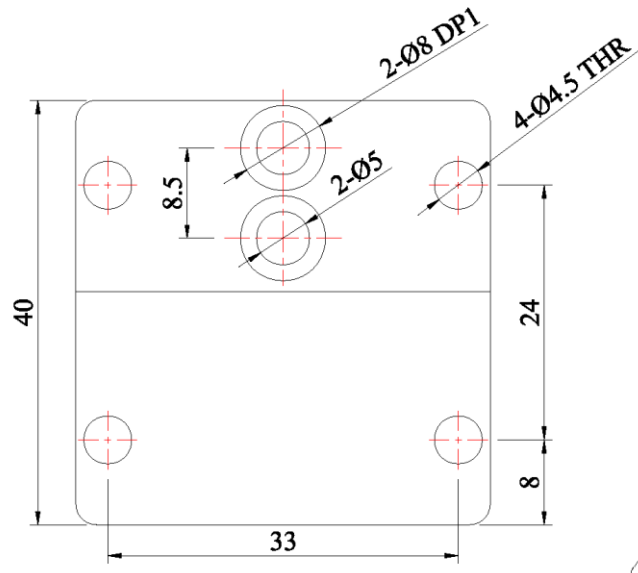
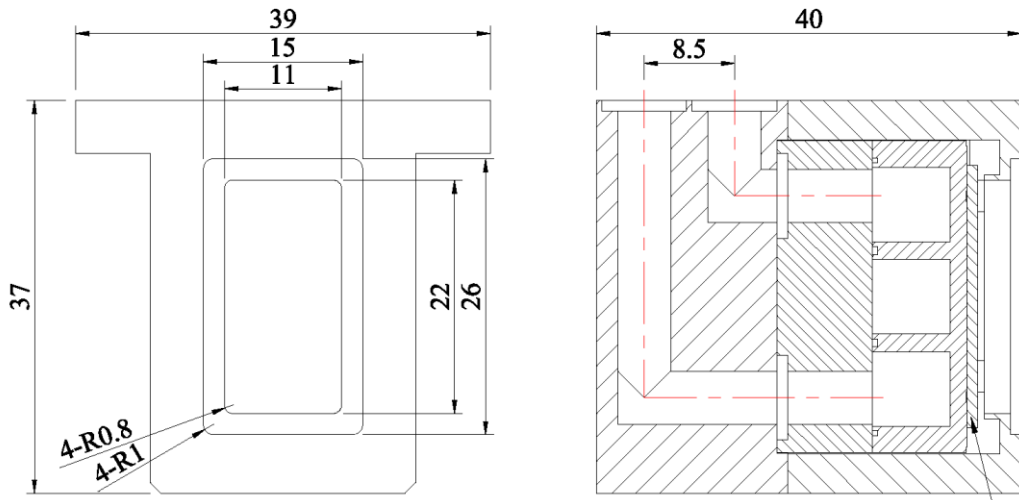


Note: Soldering procedure: The base plate is at right angles, and there is no bevel or chamfer. The copper clad and the substrate copper cannot be layered for 30 minutes at 300 degrees

VD-0808I-300W-6K-2A0 with Substrate 6=Cu and Package K=T-mount (unit: mm)

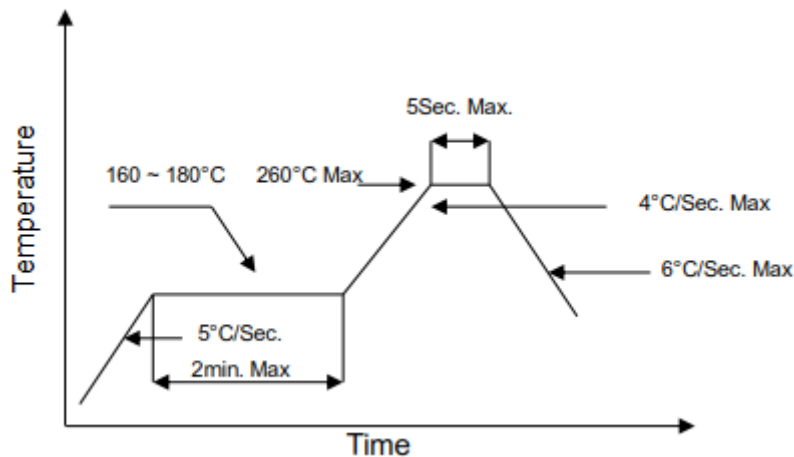


VD-0808I-300W-1U-2A0 + Water cooling with Substrate 1=AlN and Package U=1532 (unit: mm)



Note: There may be some changes between sample and drawing · thus · the actual spec please refer to the sample that you received. And if any inquires please contact us.

V. SMT Reflow Soldering Curve



Note: Reflow soldering can be operated only one time. During the temperature ramp-up, no forces may be exerted on the diode which could deform or damage them. After soldering completed, please also do not process until the product temperature ramp down to room temperature.

VI. Treatment and protection measures

Soldering precautions

The temperature of soldering iron must be controlled under 300°C during manual soldering. Also, VCSEL can be only soldered one time with the soldering time less than 3s. but, it is very hard to control the soldering temperature and homogenize solder paste because of the smaller size of VCSEL. In addition, it is easy to damage VCSEL structure even causes VCSEL losing efficacy. So, we advise you to use re-flow soldering machine for operation.

Storage precautions

Our products were sealed by aluminum foil bag attaching packed desiccant, they are moisture proof and anti-static. Please handle these gently to avoid damage. At the same time, please be ready for storage and take some moisture-proof measures to keep the diode away from dampness that may causes reliability failure.

Before opening, the diode must be saved for at least 90 days below 30 °C with 60% RH.

After opening, the diode must be kept in an environment that temperature lower than 30 °C and humidity lower than 60% RH and used up within 24 hours. When the storage humidity reaches and exceeds 60%, the products must be dehumidified at 60 °C for more than 24 hours before use.

Others

1. Please use solder paste to cure the laser diode.
2. Please make sure that the heat of the diode has been completely conducted to metal shell, to avoid affecting the optical power output.
3. This diode can be only used in constant voltage and current.
4. Operating voltage and current, refer to the table in paragraph II.
5. Please do not aim the laser to people or animal.
6. You can observe the laser spot through an image monitoring equipment.

7. Please do not touch the diode surface by naked hands or squeeze the sealant on the diode surface, or it may cause wrong optical angle and distorted laser spot, even damage the diode.
8. Please use ceramic suction nozzle to absorb the diode, to avoid the diode sticking to the nozzle.
9. Please add a 0.02 s blowing action after locating the laser diode to aluminum substrate.

VII. Revision History

Revision	Date	Description
V.01	2021/04/21	Update spec data & package [0019C4]

Note: Brightlaser reserves the right to make modification at any time due to improved design from time to time, the merit behind is to supply the best product possible.
